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Typical Applications

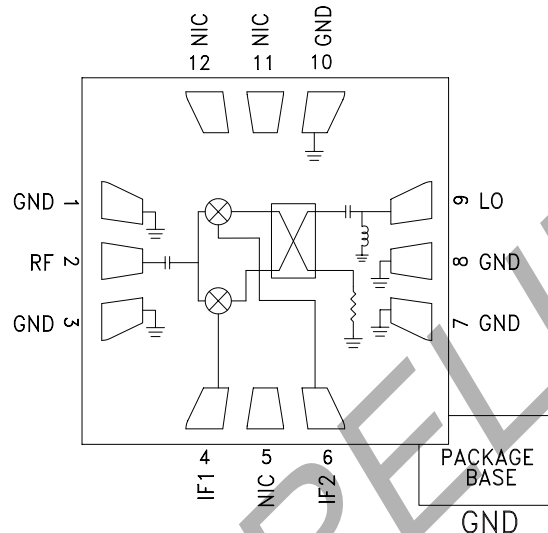
The HMC524ALC3B is ideal for:

- Point-to-Point and Point-to-Multi-Point Radios
- VSAT
- Test Equipment & Sensors
- Military End Use

Features

- Conversion Loss: 9 dB
- Image Rejection: 26 dBc
- LO to RF Isolation: 41 dB
- LO to IF Isolation: 29 dB
- Input Third-Order Intercept (IP3): 24 dBm
- Input Power for 1 dB Compression (P1dB): 14 dBm
- Wide IF Bandwidth: DC - 4.5 GHz
- 12 Lead 3 mm x 3 mm SMT Ceramic Package

Functional Diagram



General Description

The HMC524ALC3B is a compact GaAs MMIC I/Q mixer in a leadless RoHS compliant SMT ceramic package. This device can be used as either an image reject mixer or a single sideband upconverter. The mixer utilizes two standard double balanced mixer cells and a 90 degree hybrid fabricated in a GaAs MESFET process. A low frequency quadrature hybrid was used to produce a 100 MHz IF output. This product is a much smaller alternative to hybrid style image reject mixers and single sideband upconverter assemblies. The HMC524ALC3B eliminates the need for wire bonding allowing use of surface mount manufacturing techniques.

Electrical Specifications, $T_A = +25^\circ\text{C}$, IF= 100 MHz, LO Power = 17 dBm [1]

Parameter	Min.	Typ.	Max.	Units
RF Frequency Range	22		32	GHz
LO Frequency Range	22		32	GHz
IF Frequency Range	DC		4.5	GHz
LO Power		17		dBm
Conversion Loss (As IRM)		9	12	dB
Image Rejection	22	26		dB
LO to RF Isolation	35	41		dB
LO to IF Isolation	20	29		dB
Input Third-Order Intercept (IP3)	20	24		dBm
Input Power for 1 dB Compression (P1dB)		14		dBm
Amplitude Balance		±0.2		dB
Phase Balance		±4.5		Degree

[1] Unless otherwise noted all measurements performed as downconverter with lower sideband selected and external 90° IF hybrid at the IF ports.

HMC524A* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- HMC524A Evaluation Board

DOCUMENTATION

Data Sheet

- HMC524ALC3B: GaAs MMIC I/Q Mixer 22 to 32 GHz Preliminary Data Sheet

DESIGN RESOURCES

- HMC524A Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all HMC524A EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.



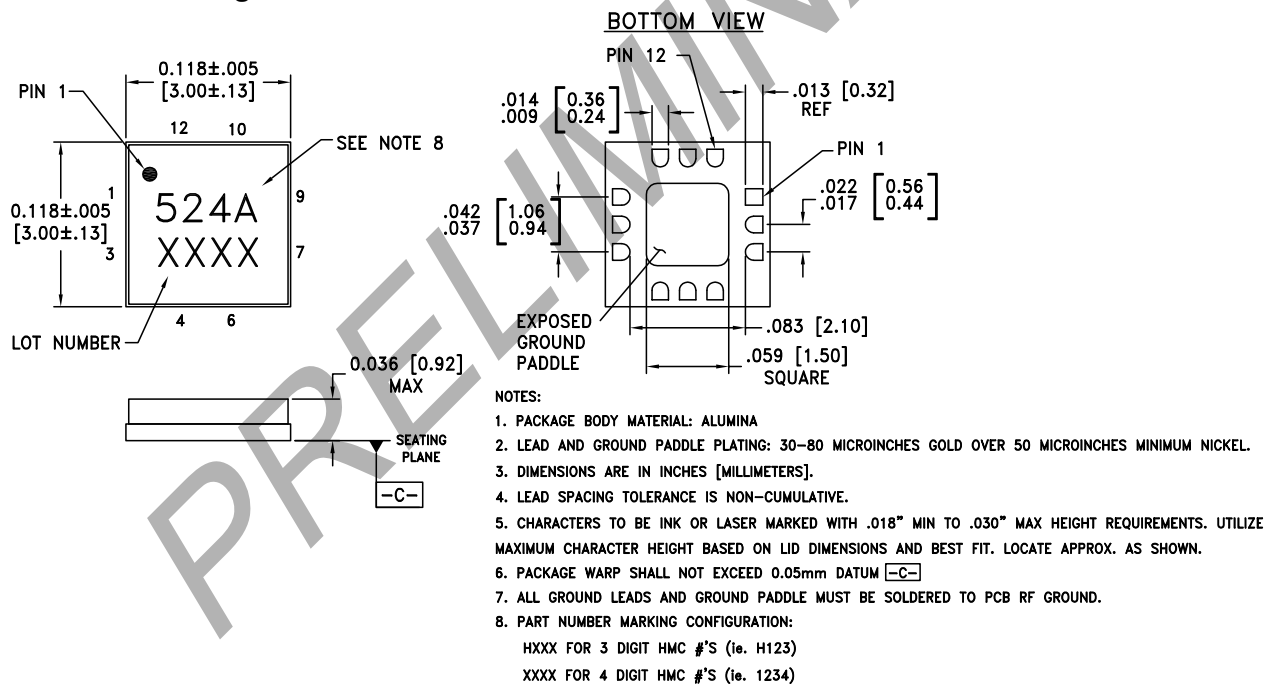
Absolute Maximum Ratings

RF Input Power	20 dBm
LO Input Power	20 dBm
LO Drive	27 dBm
Channel Temperature	150°C
Continuous Pdiss (T = 85°C) (derate (TBD) W / °C above 85 °C)	(TBD) mW
Thermal Resistance (R _{TH}) (junction to ground paddle)	(TBD) °C/W
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
ESD Sensitivity (HBM)	TBD



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Drawing



Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC524ALC3B	Alumina, White	Gold over Nickel	MSL3 ^[1]	H524A XXXX

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX

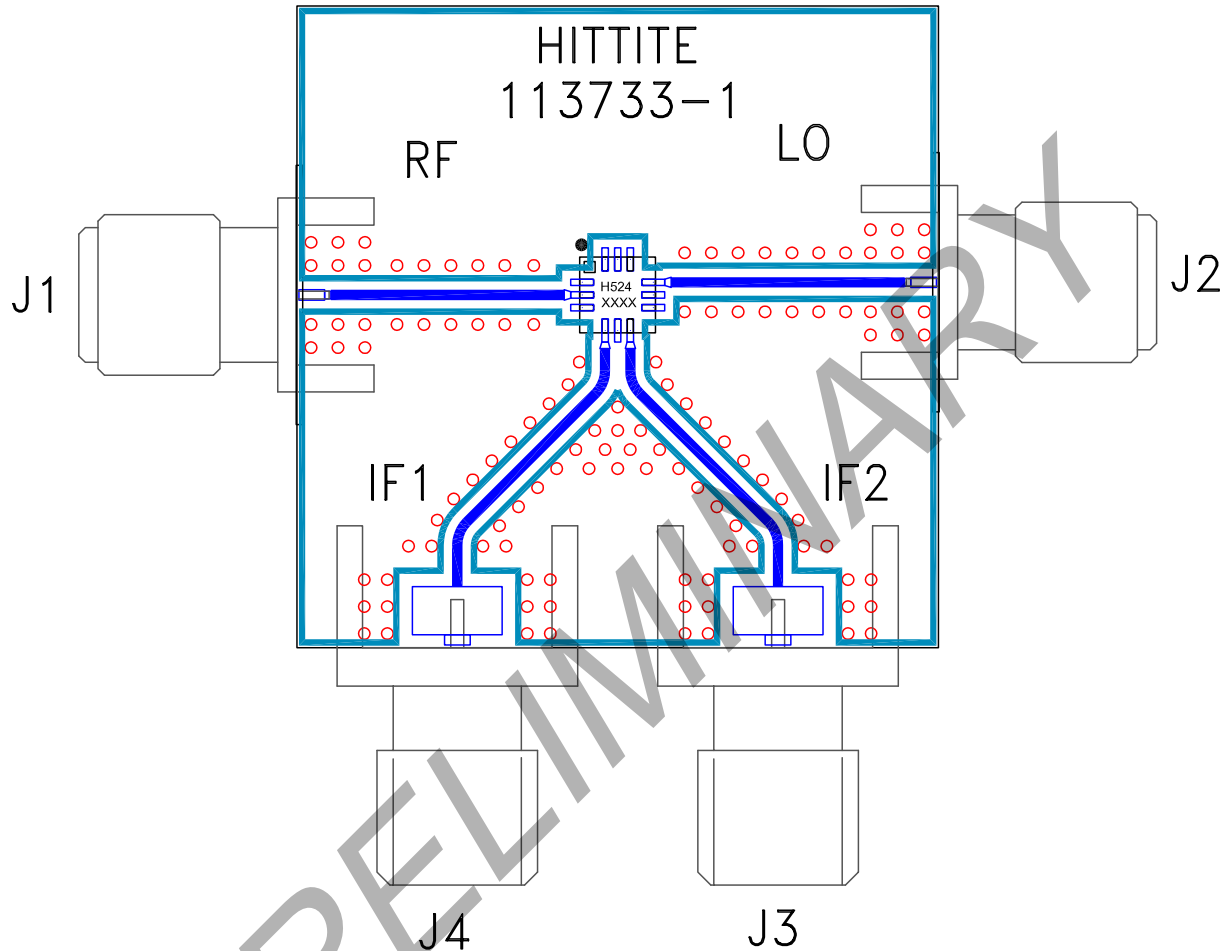


Pin Descriptions

Pin Number	Function	Description	Pin Schematic
1, 3, 7, 8, 10, 11, 12	GND	Ground Connect. These pins and package bottom must be connected to RF/dc ground.	
2	RF	Radio Frequency port This pin is ac coupled and matched to 50 Ohms.	
4	IF1	First and Second Quadrature Intermediate Frequency output pins. For applications not requiring operation to dc, an off chip dc blocking capacitor should be used. For operation to dc these pins must not source/sink more than 3 mA of current or part non function and possible part failure will result.	
6	IF2		
5	NIC	No Internal Connection. These pins are not connected internally.	
9	LO	Local Oscillator port. This pin is dc coupled and matched to 50 Ohms.	

PRELIMINARY

Evaluation PCB



Evaluation Order Information

Item	Contents	Part Number
Evaluation PCB Only	HMC524ALC3B Evaluation PCB	EV1HMC524ALC3 [1]

[1] Reference this number when ordering Evaluation PCB Only

List of Materials for Evaluation PCB

Item	Description
J1, J2	PCB Mount SMA RF Connector, SRI
J3 - J4	PCB Mount SMA Connector, Johnson
U1	HMC524LC4
PCB [1]	113733 Evaluation Board

[1] Circuit Board Material: Arlon 25FR, FR4 or Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Analog Devices upon request.